

ICS 31.200
CCS L55



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 15879.616-2026

**Mechanical standardization of semiconductor devices - Part
6-16: Glossary of semiconductor tests and burn-in sockets for
BGA, LGA, FBGA and FLGA**

半导体器件的机械标准化 第6-16部分：焊球阵列封装（BGA）、焊盘阵列封装（LGA）、密节距焊球阵列封装（FBGA）和密节距焊盘阵列封装（FLGA）的半导体试验和老化插座术语表

(English Translation)

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Table of Contents

- Foreword
- 1 Scope
- 2 Normative references
- 3 Terms and definitions

Foreword

GB/T 15879.616-2026 is a recommended national standard (GB/T) of the People's Republic of China, issued on 28 August 2026 by the State Administration for Market Regulation and the Standardization Administration of China, with effect from 1 March 2027.

The document adopts an international standard (ISO or IEC).

It is under the responsibility of the Ministry of Industry and Information Technology (Electronics).

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1 Scope

Test and burn-in sockets hold semiconductor packages during electrical testing and stress screening. This document is Part 6-16 of the series on mechanical standardization of semiconductor devices and provides a glossary of terms for such sockets used with BGA, LGA, FBGA and FLGA packages. These are area-array package types in which connections are made through solder balls or lands on the underside of the device. It adopts an international standard.

It is useful to socket manufacturers, semiconductor test and packaging houses, device makers that qualify products by burn-in, test equipment designers, and technical writers or translators who need consistent terminology. A shared glossary reduces ambiguity in specifications and supplier communication.

The document is a recommended (GB/T) standard and is voluntary unless cited in a contract or other binding document. It was issued on 28 August 2026 and takes effect on 1 March 2027.